

METHOD OF GRINDING WORKPIECE

ABSTRACT

A workpiece to be ground by a grinding wheel of a grinding apparatus has a first layer including a first material and a second layer including a second material that is harder to grind than the first material and stacked on the first layer. The rotational speed of the grinding wheel for grinding the second layer, i.e., a second rotational speed, is lower than the rotational speed of the grinding wheel for grinding the first layer, i.e., a first rotational speed. The second layer can thus be ground without hitch. As the second layer is ground in the manner described above, it is not necessary to use a grinding wheel with a high grinding capability or to lower a rate at which the workpiece is ground. Consequently, it is possible to prevent the productivity for device chips manufactured by dividing the workpiece from being lowered and also to prevent the footprint of the grinding apparatus from increasing.

[FIG. 5]